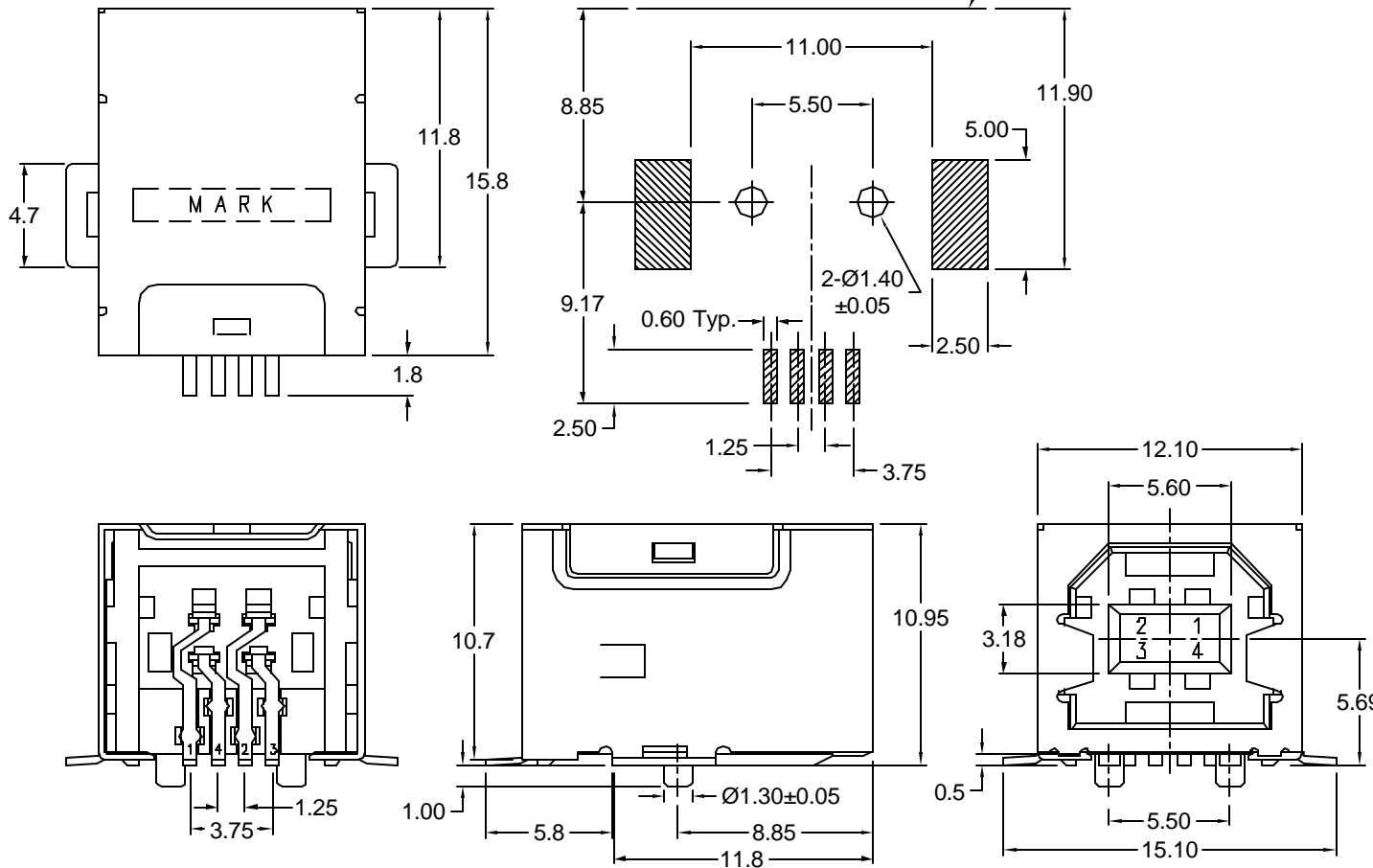


Recommended PCB Layout
(component side)



Material and Finish

Shield: Brass
Nickel plated
over copper

Insulator: UL94V-0 rated
High Temp. PA46
reflow process compatible,
Color* - white or black

Recommended Reflow Temperature:
230°C for 30 seconds
260°C maximum

Contact Material:
phosphor bronze

Contact Plating Options:
Standard: gold flash on
contact area, 120u" Tin
on solder tails, all over
50u" nickel underplate
30 Option: 30u" gold on
contact area, 120u" Tin
on solder tails, all over
50u" nickel underplate

Specifications

Rated Voltage:
30V AC (rms)

Contact Current Rating:
1A max.

Contact Resistance:
30 milliohms max.

Insulation Resistance:
1000 Megohms min.

Dielectric Withstanding:
500V AC

Insertion Force:
3.57kg max.

Extraction Force:
1.02kg min.

Operating Temperature:
-25°C to 80°C

Durability: 1500 cycles.

Part Number	Contact Area Plating Finish	*Insulator Color	Packaging
KUSBX-SMT-BS1N-W	Gold Flash (standard)	White	Bulk (trays, standard)
KUSBX-SMT-BS1N-W30	30u" Gold (30 option)	White	Bulk (trays, standard)
KUSBX-SMT-BS1N-B	Gold Flash (standard)	Black	Bulk (trays, standard)
KUSBX-SMT-BS1N-B30	30u" Gold (30 option)	Black	Bulk (trays, standard)
KUSBX-SMTBS1NWTR	Gold Flash (standard)	White	Tape-and-Reel (TR option)
KUSBX-SMTBS1NW30TR	30u" Gold (30 option)	White	Tape-and-Reel (TR option)
KUSBX-SMTBS1NBTR	Gold Flash (standard)	Black	Tape-and-Reel (TR option)
KUSBX-SMTBS1NB30TR	30u" Gold (30 option)	Black	Tape-and-Reel (TR option)



Tolerances
X.X ± 0.25
X.XX ± 0.15
Unless Stated Otherwise



REV.	DATE	DESCRIPTION	REV. BY	CHK. BY	DRAWN BY	DATE
A0	3/9/05	New Drawing	H. MA	C. Furumasa	H. AM	3/9/05
A1	5/23/05	Release Drawing	H. MA	N/A		
B1	8/29/05	ECO #05-039	R. Aguirre	H. Ma		
B2	02/21/06	ECO #06-009	R. Aguirre	H. MA		
B3	06/16/06	ECO #06-041	R. Aguirre	H. MA		

KUSBX-SMT-BS1N-xxx

UNITS
mm

Right Angle USB B-type Receptacle
SMT Type, 4 Position, RoHS Compliant

